

## CBR04C608BAGAC

CBR-SMD RF COG, Ceramic, 0.6 pF, +/-0.1 pF, 250 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0402



Click here for the 3D model.

Dimensions	
Chip Size	0402
L	1mm +/-0.05mm
W	0.5mm +/-0.05mm
Т	0.5mm +/-0.05mm
В	0.25mm +0.05/-0.1mm

Packaging Specifications		
Packaging	T&R, 180mm, Plastic Tape	
Packaging Quantity	10000	

General Information		
Series	CBR-SMD RF COG	
Style	SMD Chip	
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I	
Features	Ultra High Q, Low ESR, Class I	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Component Weight	1.4 mg	
Notes	Solder Wave or Solder Reflow.	
Shelf Life	78 Weeks	
MSL	1	

Specifications	
Capacitance	0.6 pF
Capacitance Tolerance	+/-0.1 pF
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.2%1MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	412

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